ABSTRACT OF THE DISCLOSURE

Disclosed is an electroplating solution for the deposition of silver; said solution containing silver in the form of a complex of silver with hydantoin or a substituted hydantoin compound; said solution also containing an excess of the hydantoin or substituted hydantoin compound employed, together with an effective quantity of a nonprecipitating electrolyte salt, and also an effective quantity of 2,2' dipyridyl for the purpose of obtaining a mirror-bright to brilliant deposit.

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